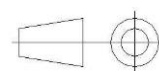
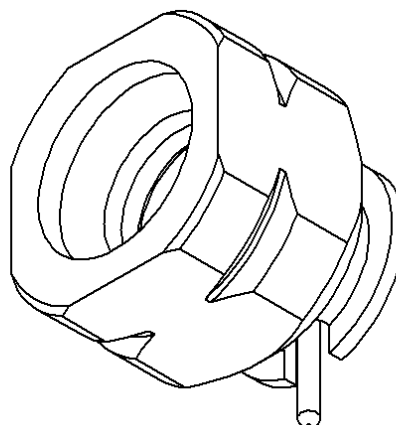
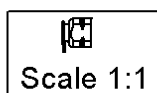
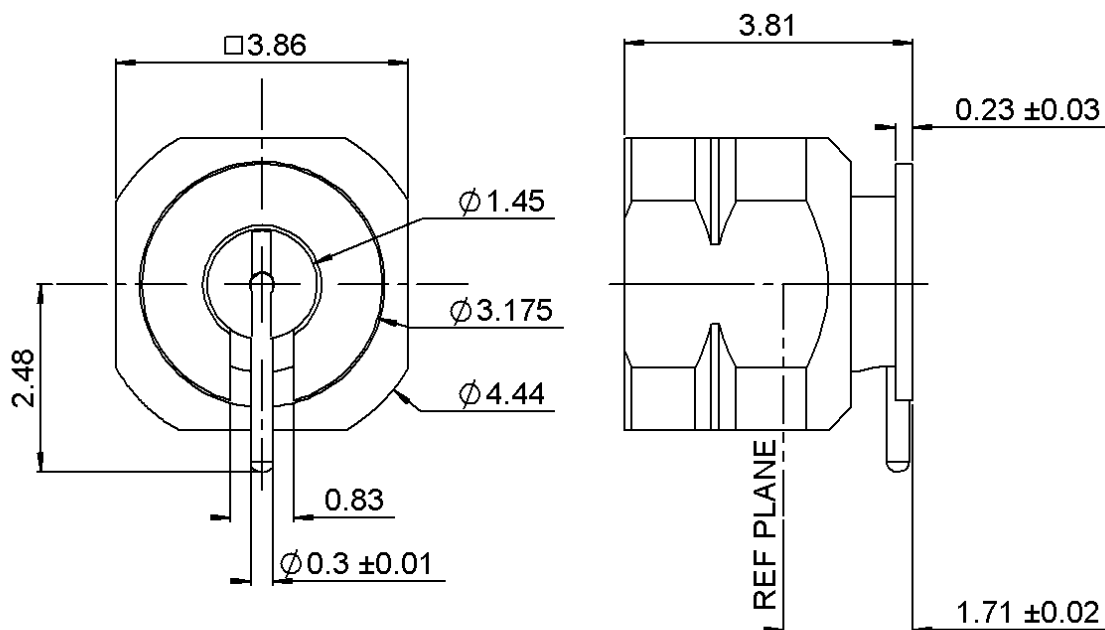


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All dimensions are in mm. Tolerances according ISO 2768 m-H

COMPONENTS	MATERIALS	PLATING (μm)
Body	<b>BERYLLIUM COPPER</b>	<b>GOLD OVER NICKEL</b>
Center contact	<b>BERYLLIUM COPPER</b>	<b>GOLD OVER NICKEL</b>
Outer contact	-	-
Insulator	<b>PEEK</b>	-
Gasket	-	-
Others parts	-	-
-	-	-
-	-	-

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## PACKAGING

Standard	Unit	Other
500	Contact us	Contact us

## ELECTRICAL CHARACTERISTICS

Impedance	50	Ω
Frequency	0-65*	GHz
VSWR	** + 0,0000	x F(GHz) Maxi
Insertion loss	0.12*	√F(GHz) dB Maxi
RF leakage	- ( NA	- F(GHz) dB Maxi
Voltage rating	335	Veff Maxi
Dielectric withstanding voltage	500	Veff mini
Insulation resistance	5000	MΩ mini

## ENVIRONMENTAL

Operating temperature	-65/+165	°C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

## MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	6.7***	N mini
Axial force – Opposite end	6.7***	N mini
Torque	NA	N.cm mini

Recommended torque		
Mating	NA	N.cm
Panel nut	NA	N.cm

Mating life	100	Cycles mini
Nominal Weight (Add +15% for max weight)	0,2720	g

## SPECIFICATION

## OTHER CHARACTERISTICS

Assembly instruction:

Others:

\*Coaxial transmission line only

\*\* 1.15 to 12GHz

\*\* 1.35 to 20GHz

\*\* Performance strongly depends on layout and PCB material

\*\*\* After soldering on PCB

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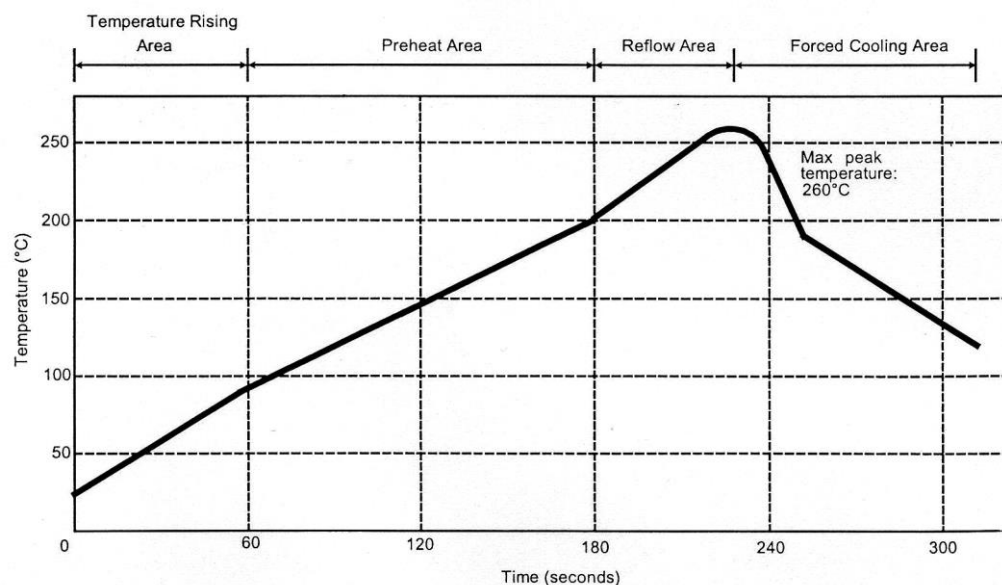
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## SOLDER PROCEDURE

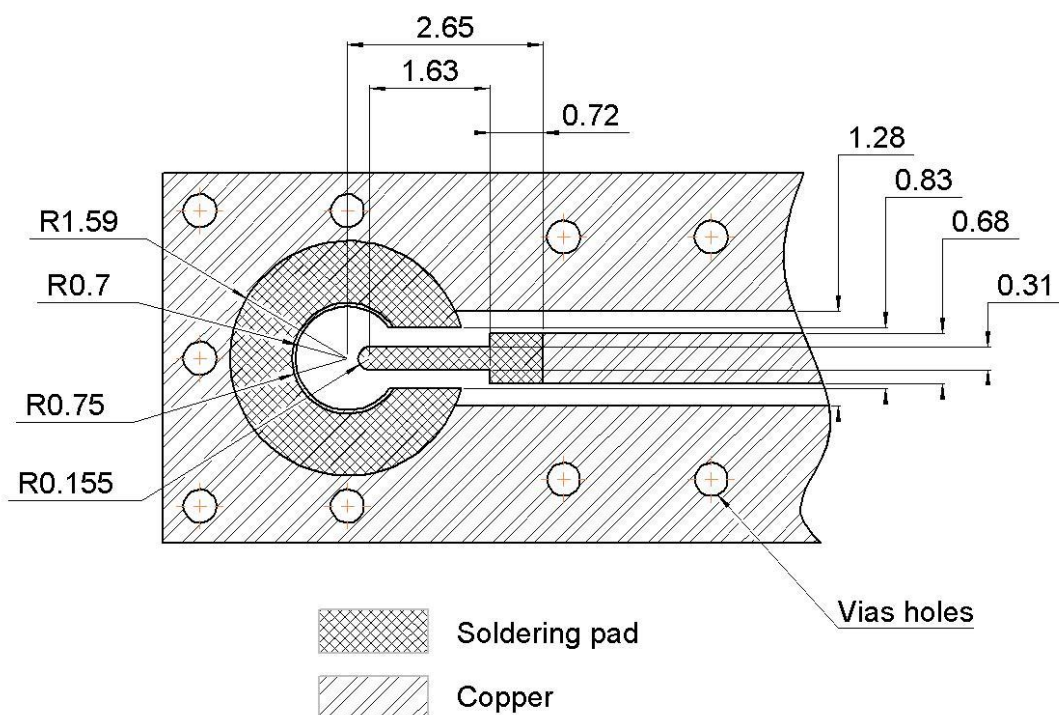
- Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application.  
We recommend a low residue flux.  
We advise a thickness of 150 µm. Verify that the edges of the zone are clean.
- Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.  
Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- Soldering by infra-red reflow.  
Below, please find the typical profile to use.
- Cleaning of printed circuit boards.
- Checking of solder joints and position of the component by visual inspection.



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

## RECOMMENDED PAD DIMENSIONS

Substrat: RT5880 thickness 0.254 mm, with copper layer 35µm on both sides.  
Add vias between both sides along upper ground plane according to engineering practise.

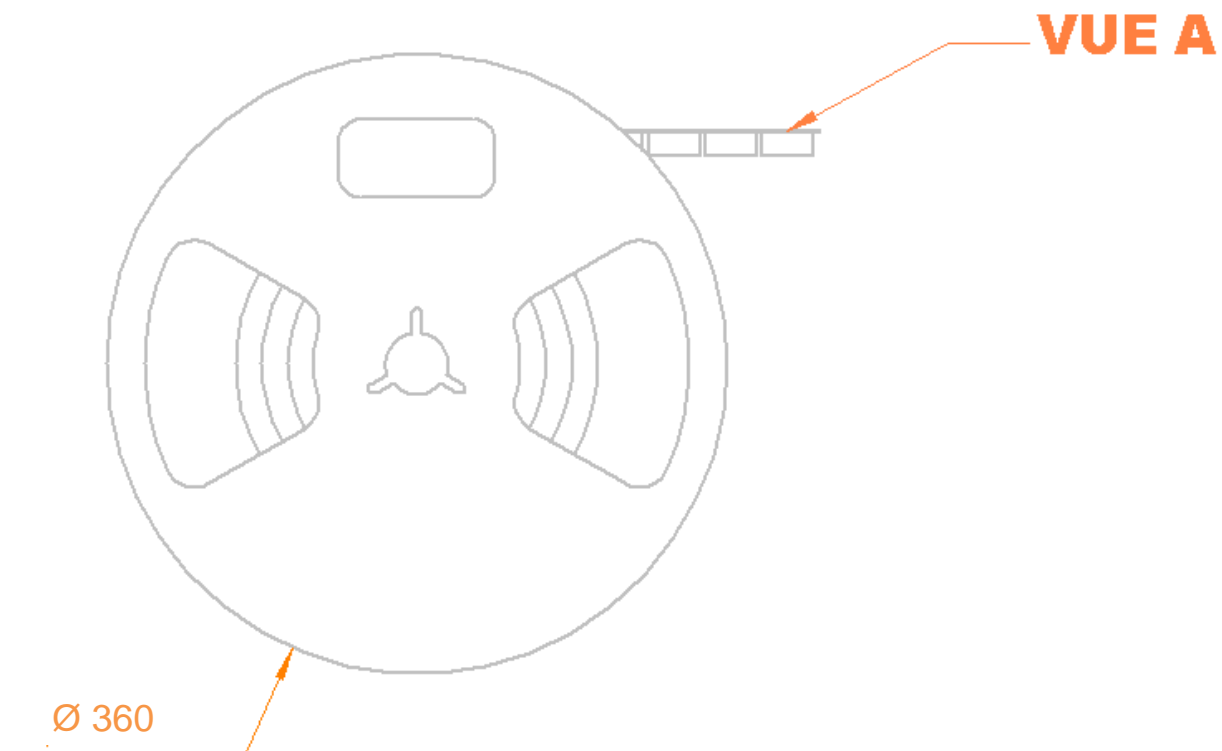


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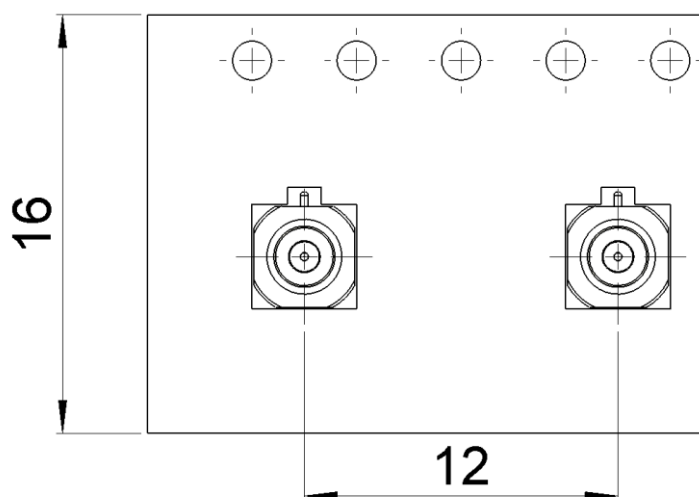
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**Vue suivant A**



**AIR SUCTION**

